

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	726305	wafer substrate	US-PGPUB; USPAT	OR	ON	2004/11/01 15:47
S2	27535	(wafer substrate) and (bond\$3 near3 pad)	US-PGPUB; USPAT	OR	ON	2004/11/01 15:48
S3	20678	((wafer substrate) and (bond\$3 near3 pad)) and wir\$3	US-PGPUB; USPAT	OR	ON	2004/11/01 15:49
S4	6055	((((wafer substrate) and (bond\$3 near3 pad)) and wir\$3) and ((thin\$6 (reduc\$3 near3 thickness)) with (wafer substrate)))	US-PGPUB; USPAT	OR	ON	2004/11/01 15:50
S5	1452	(((((wafer substrate) and (bond\$3 near3 pad)) and wir\$3) and ((thin\$6 (reduc\$3 near3 thickness)) with (wafer substrate)))) and (solder near5 bump)	US-PGPUB; USPAT	OR	ON	2004/11/08 18:46
S6	719	(((((wafer substrate) and (bond\$3 near3 pad)) and wir\$3) and ((thin\$6 (reduc\$3 near3 thickness)) with (wafer substrate)))) and (solder near5 bump)) and (singulat\$3 dic\$3)	US-PGPUB; USPAT	OR	ON	2004/11/03 11:15
S7	721	(((((wafer substrate) and (bond\$3 near3 pad)) and wir\$3) and ((thin\$6 (reduc\$3 near3 thickness)) with (wafer substrate)))) and (solder near5 bump)) and (singulat\$3 dic\$3)	US-PGPUB; USPAT	OR	ON	2004/11/03 11:33
S8	17	(((((wafer substrate) and (bond\$3 near3 pad)) and wir\$3) and ((thin\$6 (reduc\$3 near3 thickness)) with (wafer substrate)))) and (solder near5 bump)) and (singulat\$3 dic\$3)) and shim	US-PGPUB; USPAT	OR	ON	2004/11/03 11:17
S9	37	(((((wafer substrate) and (bond\$3 near3 pad)) and wir\$3) and ((thin\$6 (reduc\$3 near3 thickness)) with (wafer substrate)))) and (solder near5 bump)) and (singulat\$3 dic\$3)) and (screw shim)	US-PGPUB; USPAT	OR	ON	2004/11/03 11:34
S10	0	(((((wafer substrate) and (bond\$3 near3 pad)) and wir\$3) and ((thin\$6 (reduc\$3 near3 thickness)) with (wafer substrate)))) and (solder near5 bump)) and (singulat\$3 dic\$3)) and (screw shim)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/03 11:34
S11	409	(((((wafer substrate) and (bond\$3 near3 pad)) and wir\$3) and ((thin\$6 (reduc\$3 near3 thickness)) with (wafer substrate)))) and (solder near5 bump)) and (singulat\$3 dic\$3)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/03 11:36

S12	0	(((wafer substrate) and (bond\$3 near3 pad)) and wir\$3) and ((thin\$6 (reduc\$3 near3 thickness)) with (wafer substrate))) and (solder near5 bump)) and (singulat\$3 dic\$3)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/03 11:36
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